

JUN 22 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

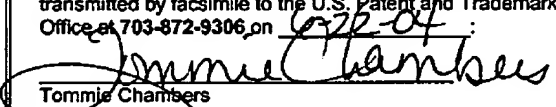
Applicant: Yoshino
Serial No: 09/909,013
Filed: 7/19/2001
For: SEMICONDUCTOR PACKAGE INSULATION FILM AND
MANUFACTURING METHOD THEREOF

Docket No: TI-29448
Examiner: Geyer, Scott
Art Unit: 2829

OFFICIAL

EXTENSION OF TIME

Assistant Commissioner For Patents
Washington, DC 20231

<p align="center">CERTIFICATION OF FACSIMILE TRANSMISSION</p> <p>I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on <u>6/22/04</u>:</p> <p align="center"> Tommie Chambers</p>

Dear Sir:


Pursuant to 37 CFR 1.136(a), Applicant(s) respectfully petition(s) the Commissioner for an extension of the shortened statutory period for response in the above identified Application.

The fee for this extension is indicated below:

<input checked="" type="checkbox"/> One Month (\$110)	<input type="checkbox"/> Three Months (\$890)
<input type="checkbox"/> Two Months (\$390)	<input type="checkbox"/> Four Months (\$1,390)

Any further necessary extension of time is hereby requested. Charge any and all fees, or credit any overpayment, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,


W. Daniel Swayze, Jr.
Attorney for Applicant
Reg. No. 34,478

Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265
(972) 917-5633

To: T chonology Unit: 2829
Facsimile Number: 703-872-9306

Total Pages Sent 12

From: W. Daniel Swayze, Jr.
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-5633

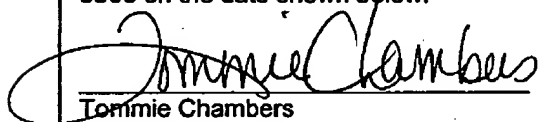
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Tommie Chambers Date 6-22-04

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT (12 Pages)
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT (1 Month)
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<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Yoshino	
RECEIPT DATE & SERIAL NO.: Serial No.: 09/909,013 Filing Date: 7/19/2001	
TITLE OF INVENTION: SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING METHOD THEREOF	
TI FILE NO.: TI-29448	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6-22-04 DUE: 05/27/04 ATTY/SEC'Y: WDS/nc	

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Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265